External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	1.49421	100.0	0.45
			Subtotal	1.49421	100	0.45
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02865	0.03	0.00863
	Copper alloy	Iron (Fe)	7439-89-6	0.0955	0.1	0.02876
	Copper alloy	Copper (Cu)	7440-50-8	95.32486	99.82	28.70823
	Copper alloy	Silver (Ag)	7440-22-4	0.04775	0.05	0.01438
			Subtotal	95.49676	100	28.76
Mould Compound	Polymer	Epichlorohydrin/o- Cresol/Formaldehyde polymer (generic)	29690-82-2	0	11.5	0
	Filler	Silica -amorphous-	7631-86-9	0	8.0	0
	Filler	Silica fused	60676-86-0	0	80.0	0
	Carbon Black	Carbon black	1333-86-4	0	0.5	0
			Subtotal	0	100	0
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	2.85561	100.0	0.86
			Subtotal	2.85561	100	0.86
Die Attach		2-Butoxyethyl acetate	112-07-2	0	8.0	0
	Polymer	Epoxy resin system		0	8.0	0
	Lead alloy	Silver (Ag)	7440-22-4	0	84.0	0
			Subtotal	0	100	0
Wire	Impurity	Non hazardous		0.00002	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.15341	99.99	0.0462
			Subtotal	0.15343	100	0.0462
			Total	100.00001	100	30.1162

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